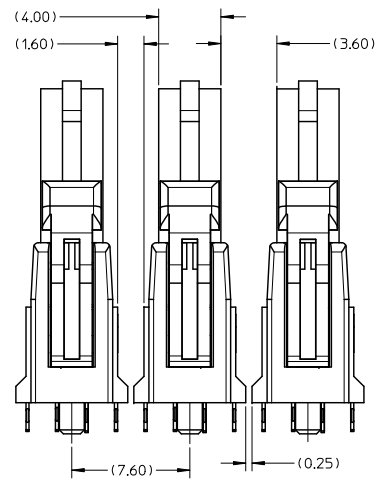
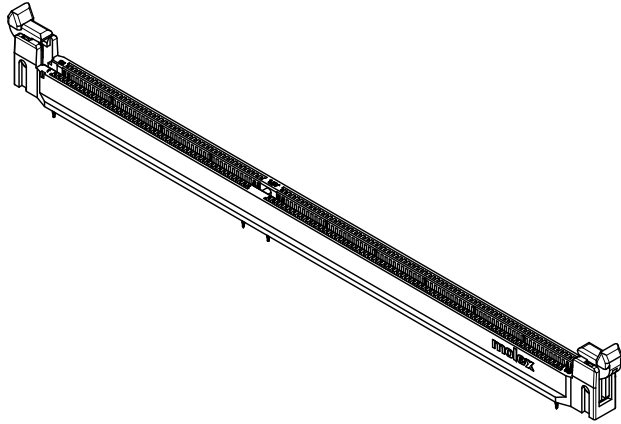
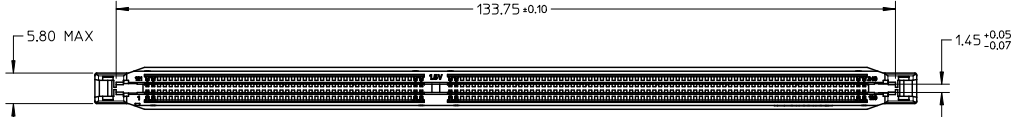


- NOTES:
- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
- MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
 - MODULE SEATING PLANE FROM TOP OF PCB
 - KEEP OUT ZONE RESERVED FOR LATCH

ADDED OPTION	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
				mm	INCH	MM ONLY	NTS	METRIC		
4 PLACES ± --- ± ---			▽=0			DRAWN BY	DATE	TITLE		
3 PLACES ± --- ± ---			▽=0			CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)		
2 PLACES ± 0.20 ± ---			▽=0			CCTEH	2008/07/30	1.00MM PITCH, 240 CKTS		
1 PLACE ± --- ± ---			▽=0			APPROVED BY	DATE	MOLEX INCORPORATED		
ANGULAR ± 1 °						SHLENI	2010/12/15			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						MATERIAL NO.		MOLEX INCORPORATED		
						SEE TABLE		SD-78315-001		
						SIZE				
						A3				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

tb_frame_A3_P_AM_T
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10 9 8 7 6 5 4 3 2 1



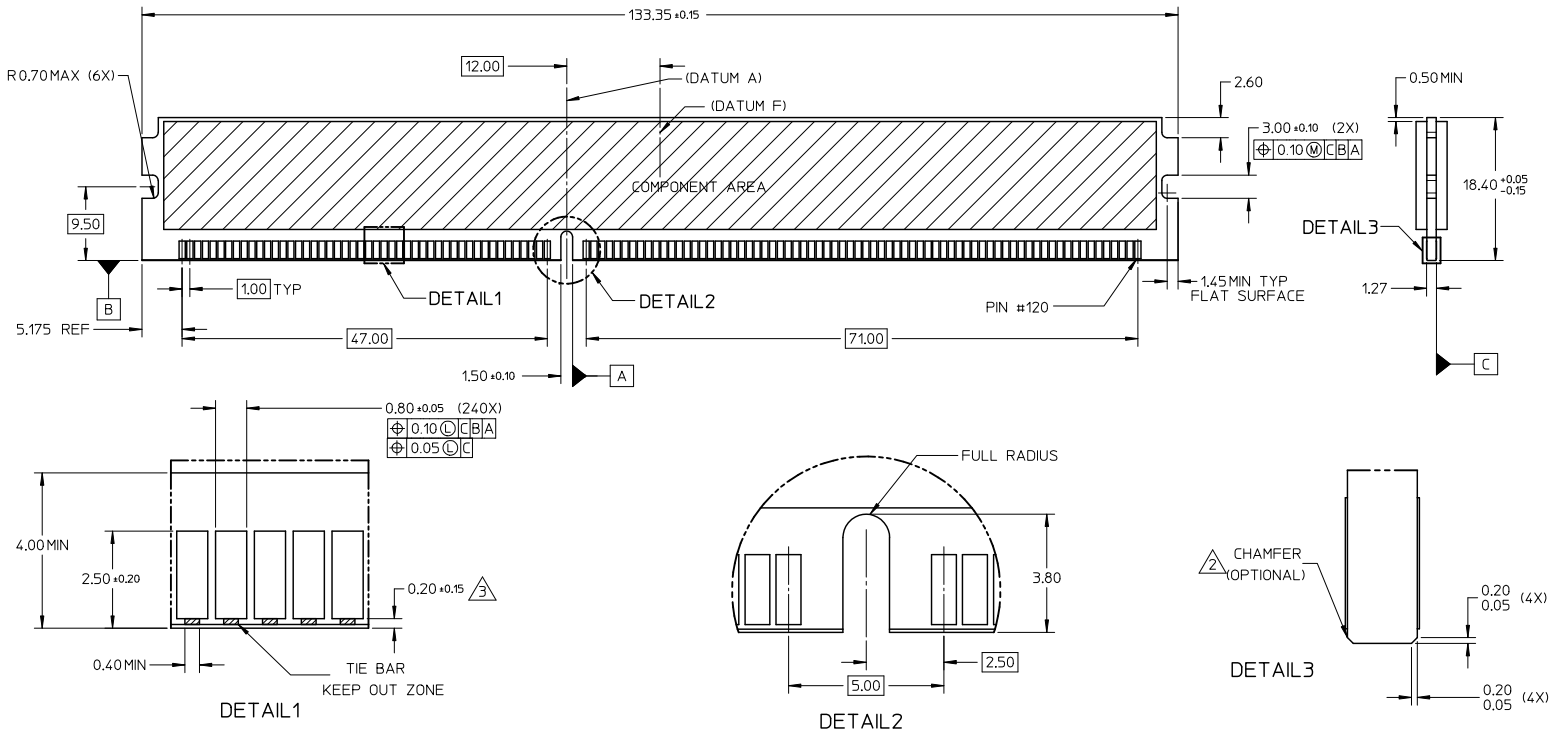
MINIMUM ROW TO ROW SPACING RECOMMENDATION (USING 4.00MM MODULE CARD)

ADDED OPTION EC NO: S2011-0814 DRAWN: CTEH CHECKED: SHLENI APPR: SHLENI 2011/02/08 2011/04/04 2011/04/04	DESCRIPTION A1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		∇=0 ∇=0 ∇=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1°	MM ONLY	NTS	METRIC	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR
		DRAWN BY: CMTEO CHECKED BY: CTEH APPROVED BY: SHLENI	DATE: 2008/07/17 DATE: 2008/07/30 DATE: 2010/12/15	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 2 OF 6	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					MOLEX INCORPORATED

tb_frame_A3_P_AM_T
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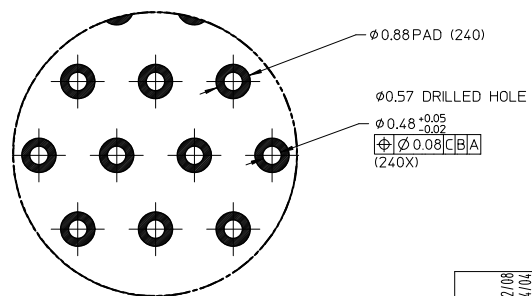
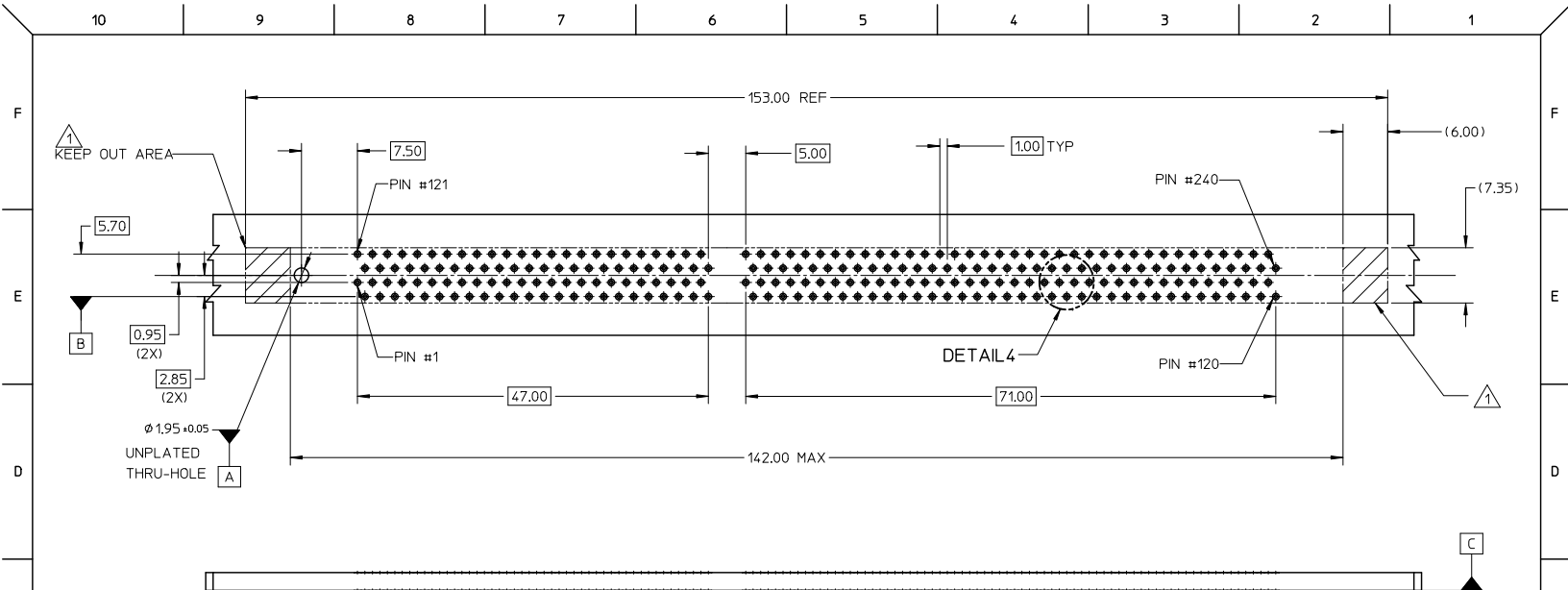
9 8 7 6 5 4 3 2 1

009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT
- △ CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
 △ LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

ADDED OPTION IEC NO: SZ2011-0814 DRAWN: CTEH 2011/07/08 CHECKED: CHYK:CGIAN 2011/06/04 APPR: SHLENI 2011/04/04 REV: A1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± --- ± ---	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR	
	▽=0	3 PLACES ± --- ± ---	CHECKED BY CTEH	DATE 2008/07/30	MOLEX INCORPORATED	
	▽=0	2 PLACES ± 0.20 ± ---	APPROVED BY SHLENI	DATE 2010/12/15		DOCUMENT NO. SD-78315-001
		1 PLACE ± --- ± ---	MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		ANGULAR ± 1°	SIZE A 3			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

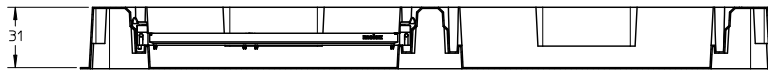
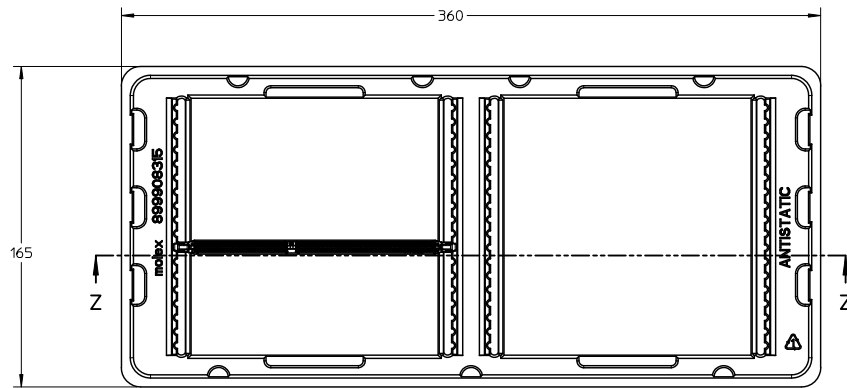


NOTES:
 1. KEEPOUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

ADDED OPTION EC NO: S2011-0814 DRAWN: CCTEH CHYK: CCGIAN APPR: SHLENI 2011/02/08 2011/06/04 2011/04/04	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
		4 PLACES	±	---	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED		
		3 PLACES	±	---	APPROVED BY SHLENI	DATE 2010/12/15	DOCUMENT NO. SD-78315-001		
2 PLACES	±	0.20	MATERIAL NO. SEE TABLE		SHEET NO. 4 OF 6				
1 PLACE	±	---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR		±	1°						

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

NOTE:
1. NO. OF CAVITY - 18 X 2 = 36

ADDED OPTION EC NO: S2011-0814 DRAWN: CTEH 2011/02/08 CHKD: CGTAN 2011/04/04 APPR: SHLENI 2011/04/04 A1	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED		
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2010/12/15	DOCUMENT NO. SD-78315-001	SHEET NO. 5 OF 6	
			2 PLACES	± 0.20	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
			1 PLACE	± ---	± ---	MATERIAL NO. SEE TABLE			
			ANGULAR ± 1 °		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

PART NO.	KEY POS	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION		LATCH COLOUR	HOUSING COLOUR
				CONTACT AREA	TAIL AREA		
78315-0001	CENTER (15V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78315-0051						BLUE	BLUE
78315-0201		2.85	2.60	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN/LEAD (BRIGHT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78315-0011						BLACK	BLACK

ADDED OPTION EC NO: S2011-0814 DRWNG: CTEH 2011/02/08 CHKD: CGTAN 2011/04/04 APPR: SHLENI 2011/04/04	DESCRIPTION REV A1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION																				
		$\nabla=0$ $\nabla=0$ $\nabla=0$	<table border="1"> <tr><th colspan="2">mm</th><th colspan="2">INCH</th></tr> <tr><td>4 PLACES</td><td>± ---</td><td>± ---</td><td>± ---</td></tr> <tr><td>3 PLACES</td><td>± ---</td><td>± ---</td><td>± ---</td></tr> <tr><td>2 PLACES</td><td>± 0.20</td><td>± ---</td><td>± ---</td></tr> <tr><td>1 PLACE</td><td>± ---</td><td>± ---</td><td>± ---</td></tr> </table>	mm		INCH		4 PLACES	± ---	± ---	± ---	3 PLACES	± ---	± ---	± ---	2 PLACES	± 0.20	± ---	± ---	1 PLACE	± ---	± ---	± ---	MM ONLY	NTS	METRIC	
		mm		INCH																							
		4 PLACES	± ---	± ---	± ---																						
3 PLACES	± ---	± ---	± ---																								
2 PLACES	± 0.20	± ---	± ---																								
1 PLACE	± ---	± ---	± ---																								
DRAWN BY: CMTEO CHECKED BY: CCTEH APPROVED BY: SHLENI	DATE: 2008/07/17 DATE: 2008/07/30 DATE: 2010/12/15	TITLE	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR																								
MATERIAL NO. SEE TABLE SIZE A3		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED		DOCUMENT NO. SD-78315-001	SHEET NO. 6 OF 6																				

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Rev. F 2009/06/18

9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1